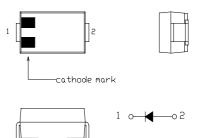
Nihon Inter Electronics Corporation

SBD Type: EC21QS06

FEATURES

- * Miniature Size, Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC21QS06			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	60			V
Non- repetitive Peak Reverse Voltage	V_{RSM}	65			V
Average Rectified Output Current	Io	1.0 2.0	Ta=35 °C *1 TI=90 °C	50Hz Half Sine Wave Resistive Load	Α
RMS Forward Current	I _{F(RMS)}	3.14			Α
Surge Forward Current	I _{FSM}	40	50Hz Half Sine Wave,1cycle Non-repetitive		Α
Operating JunctionTemperature Range	T_{jw}	-40 to +150			°C
Storage Temperature Range	T _{stg}	-40 to +150			°C

Electrical • Thermal Characteristics

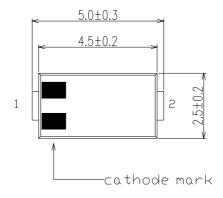
Ch	aracteristics	Symbol	Conditions		Тур.	Max.	Unit
Peak Reve	ak Reverse Current I _{RM} Tj= 25°C, V _{RM} = V _{RRM}		-	-	2	mA	
Peak Forv	K Forward Voltage V _{FM} Tj= 25°C, I _{FM} = 2.0A		-	-	0.61	V	
Thermal	Junction to Ambient	Rth _(j-a)	Alumina Substrate Mounted *1	-	-	108	°C /W
Resistance	Junction to Lead	Rth _(j-l)	-	-	-	23	C/VV

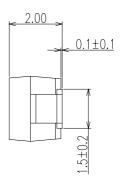
^{*1} Alumina Substrate Mounted (Soldering Lands=2x2mm,Both Sides)

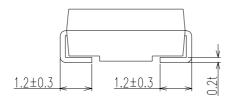
(TI: Lead Temperature)

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EC21QS06 OUTLINE DRAWING (Dimensions in mm)









soldering pad

